

IN THE CLAIMS:

Please cancel claims 4 and 10 without prejudice to or disclaimer of the subject matter presented therein. Please amend claims 3, 6 and 7, as shown below. The claims, as pending in the subject application, read as follows:

1 and 2. (Cancelled)

3. (Currently Amended) A semiconductor device manufacture method comprising:

a step of bonding a first substrate and a second substrate having a light reception element by using a spacer; and

a step of cutting the first and second substrates,

wherein said ~~step of cutting the first substrate cutting step~~ cuts the first substrate at a position where the spacer is disposed under the first ~~substrate~~ substrate,

wherein an electrode pad is disposed on at least one side of the second substrate, and the spacer is disposed on the same side on which the electrode is disposed, such that after said cutting step is effected, the spacer is disposed inwards of the electrode pad.

4. (Cancelled)

5. (Original) A semiconductor device manufacture method according to claim 3, wherein the first substrate is formed with a plurality of lenses.

6. (Currently Amended) A semiconductor device manufacture method comprising:

a step of holding the semiconductor substrate on a base under a condition that the a warp of the semiconductor substrate is removed;

a step of bonding an opposing substrate to the semiconductor substrates substrate with a size of the opposing substrate being adjusted according to the warp of the semiconductor substrate; and then

a step of cutting the opposing substrate substrate,

wherein the semiconductor substrate is formed with a light reception element or light reception elements, and the opposing substrate is formed with an optical element or optical elements, with the optical element or optical elements being set for converging light on the light reception element or light reception elements.

7. (Currently Amended) A semiconductor device manufacture method according to claim 6, comprising a step of bonding a plurality of opposing substrates to the semiconductor substrate with a gap of a between said plurality of opposing substrate substrates corresponding to the size of the warp of the semiconductor substrate.

8. (Original) A semiconductor device manufacture method according to claim 6, wherein said step of bonding the opposing substrate to the semiconductor substrate uses a spacer disposed between the opposing substrate and the semiconductor substrate.

9. (Original) A semiconductor device manufacture method according to claim 6, wherein said step of cutting the opposing substrate cuts an area of the opposing substrate where a spacer is disposed under the opposing substrate.

10. (Cancelled)

11. (Original) A semiconductor device manufacture method according to claim 6, wherein the opposing substrate is formed with a compound eye element having a plurality of lenses.

12. (Original) A semiconductor device manufacture method according to claim 6, wherein the semiconductor substrate is a semiconductor wafer.

13. (Original) A semiconductor device manufacture method according to claim 6, wherein the opposing substrate has a rectangular shape, a cross shape, a T-character shape, an I-character shape, an L-character shape or a polygonal shape.